RoHS

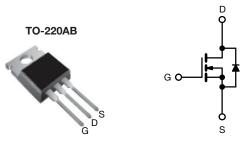
COMPLIANT HALOGEN

FREE



www.vishay.com

EF Series Power MOSFET With Fast Body Diode

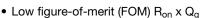


N-Channel	MOSEET
N-Channel	MOSEE

PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.084		
Q _g max. (nC)	134			
Q _{gs} (nC)	16			
Q _{gd} (nC)	48			
Configuration	Single			

FEATURES

• A specific on resistance (m Ω -cm 2) reduction of 25 %



- Low input capacitance (C_{iss})
- · Reduced switching and conduction losses
- Ultra low gate charge (Qq)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and halogen-free	SiHP35N60EF-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	600	V	
Gate-source voltage			V_{GS}	± 30	\	
Continuous drain current (T _J = 150 °C)	V at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I _D	32	A	
	V _{GS} at 10 V	T _C = 100 °C		20		
Pulsed drain current ^a			I _{DM}	80	ı	
Linear derating factor				2.0	W/°C	
Single pulse avalanche energy ^b			E _{AS}	298	mJ	
Maximum power dissipation			P _D	250	W	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope	T _J = 125 °C		dv/dt	70	V/ns	
Reverse diode dv/dt ^d			uv/dt	50	V/IIS	
Soldering recommendations (peak temperature) c	For 10 s			260	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4.6 A
- c. 1.6 mm from case
- d. $I_{SD} = 17 \text{ A}$, $di/dt = 300 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$



Vishay Siliconix

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	62	°C/W
Maximum junction-to-case (drain)	R_{thJC}	-	0.5	G/ V V

PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I _D = 10 mA		0.66	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		-	4.0	V
Cata assuma laglanda		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I_{GSS}	,	$V_{GS} = \pm 30 \text{ V}$		-	± 1	μΑ
Zava sata valtasa duain ayuwant	1	V _{DS} =	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	, V _{GS} = 0 V, T _J = 125 °C	-	-	500	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 17 A	-	0.084	0.097	Ω
Forward transconductance ^a	9 _{fs}	V _{DS}	= 30 V, I _D = 17 A	-	8	-	S
Dynamic							
Input capacitance	C _{iss}	V _{GS} = 0 V,		-	2568	-	-
Output capacitance	C _{oss}	,	$V_{DS} = 0 V_{r}$, $V_{DS} = 100 V_{r}$,		113	-	
Reverse transfer capacitance	C _{rss}	f = 1 MHz		-	7	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	81	-	pF
Effective output capacitance, time related ^b	C _{o(tr)}			-	421	-	
Total gate charge	Qg			-	89	134	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 17 \text{ A}, V_{DS} = 480 \text{ V}$		16	-	nC
Gate-drain charge	Q _{gd}				48	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 480 V, I _D = 17 A,		-	28	56	
Rise time	t _r			-	85	170	
Turn-off delay time	t _{d(off)}		$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		96	192	ns
Fall time	t _f			-	61	122	
Gate input resistance	R _g	f = 1 MHz, open drain		0.2	0.5	1.0	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	32	
Pulsed diode forward current	I _{SM}			-	-	80	A
Diode forward voltage	V _{SD}	T _J = 25 °C	T _J = 25 °C, I _S = 17 A, V _{GS} = 0 V		-	1.2	V
Reverse recovery time	t _{rr}	-		-	150	300	ns
Reverse recovery charge	Q _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 17 \text{ A},$ $di/dt = 100 \text{ A/µs}, V_R = 400 \text{ V}$		-	1.1	2.2	μC
Reverse recovery current	I _{RRM}			_	14	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

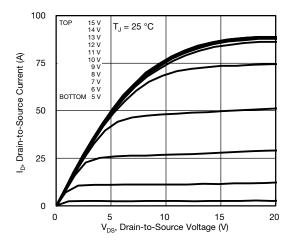


Fig. 1 - Typical Output Characteristics

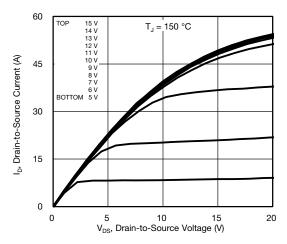


Fig. 2 - Typical Output Characteristics

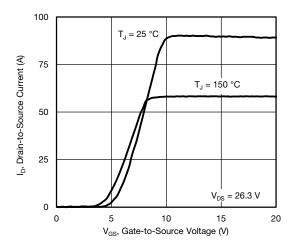


Fig. 3 - Typical Transfer Characteristics

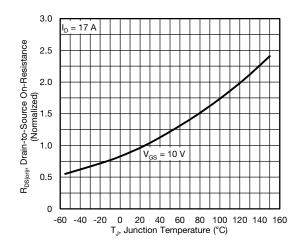


Fig. 4 - Normalized On-Resistance vs. Temperature

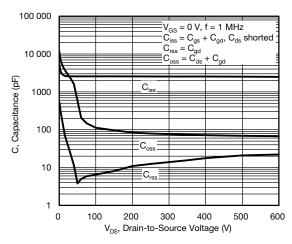


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

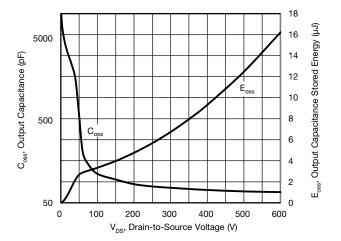


Fig. 6 - Coss and Eoss vs. VDS



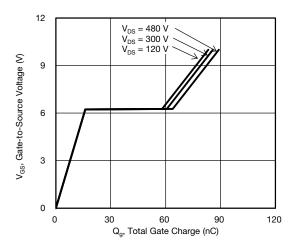


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

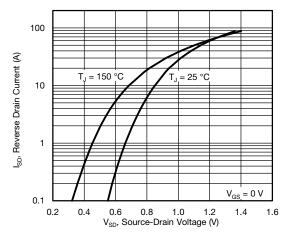


Fig. 8 - Typical Source-Drain Diode Forward Voltage

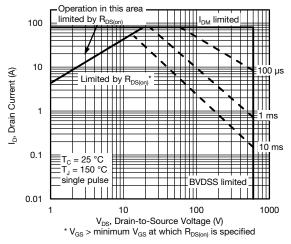


Fig. 9 - Maximum Safe Operating Area

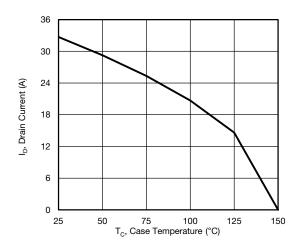


Fig. 10 - Maximum Drain Current vs. Case Temperature

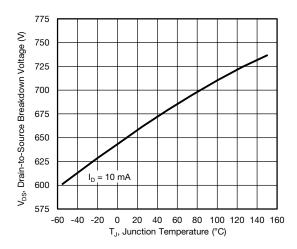


Fig. 11 - Temperature vs. Drain-to-Source Voltage



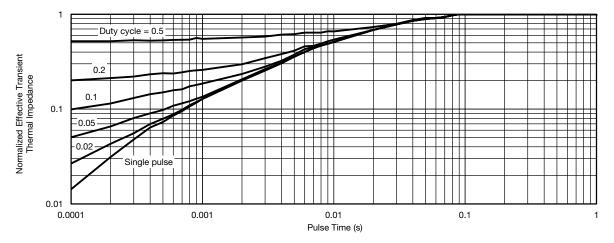


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

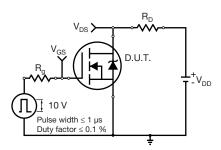


Fig. 13 - Switching Time Test Circuit

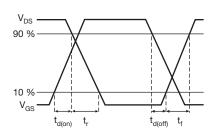


Fig. 14 - Switching Time Waveforms

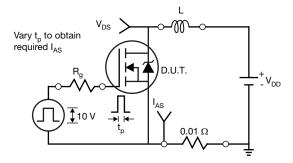


Fig. 15 - Unclamped Inductive Test Circuit

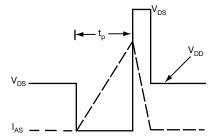


Fig. 16 - Unclamped Inductive Waveforms

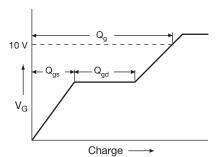


Fig. 17 - Basic Gate Charge Waveform

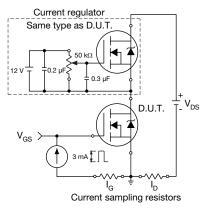


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit

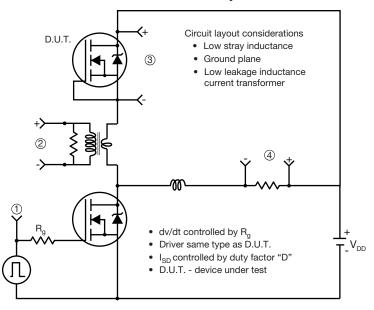




Fig. 19 - For N-Channel

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